ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan	C. Bannockl	burn, Illinois, A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declaration entite the declaration entities and the declaration entite the declaration entit entits entite the declaration entite the declaration entit	on of the su compasses	ibstances v s all lower	within the manufactu level materials for w	rer listed i	tem. Note: nanufacture	if the item is an as er has engineering	sembly with lowe responsibility.
T52 21 1 IPC Web Site for Information on IPC-1752 Standard Form T				Form Type * Distribute	*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Information													
Company name* Company unique ID					Unique ID Authority			Response Date*					
onsemi						2022-02-10							
Contact Name Title - Contact			t			Phone - Contact*				Email - Contact*			
Product-Env-Stewards P			Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* T			Fitle - Representative			Phone - Representative*			Email -	Email - Representative*			
Product-Env-Stewards	Product Envir	Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com					
Requester Item Number	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Date	Version	N	Manufacturing Site		Weight*	UOM	Unit Type
	AR0147 A0-DPB	7ATSC00XUE 1MP 1/4 CIS SO BR				2022-02-10		N	MY5		229.3	mg	Each
Manufacturing Proccess Informat	ion												
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020			J-STD-020 MSL	Rating	Peak Proce	ss Body Te	emperatur	e Max Time at Peak	Tempera	ture Num	ber of Reflow Cyc	cles	
SnAgCu CU Alloy 3			3		260		С	30	secor	nds 3			
Comments													
ATTENTION: MSL 3 Rated item requires	Bake and L	Dry Pack (after	electrical test)										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	18.5	mg		Misc.	proprietary data		0.0703	mg
			Supplier	Silicon (Si)	7440-21-3		18.2465	mg
			Supplier	Aluminum (Al)	7429-90-5		0.1831	mg
Die Attach	2.8	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		1.05	mg
			Supplier	Ethylene Glycol	107-21-1		0.028	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.084	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.588	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.05	mg
Imaging Lens	28.48	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.4989	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.4989	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.4989	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1501	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.4989	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.4989	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		20.8354	mg
Lid Attach	1.46	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.657	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.292	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.1825	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.0073	mg
			Supplier	Curative	Proprietary Data		0.0292	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.292	mg
Mold Compound-Black	81.6	mg		Phenolic Resin	proprietary data		12.24	mg
			Supplier	Oxirane	39817-09-9		12.24	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		2.448	mg
			Supplier	Carbon Black (C)	1333-86-4		0.816	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		52.224	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.632	mg
Solder Ball	46.7	mg	Supplier	Silver (Ag)	7440-22-4		1.401	mg
			Supplier	Tin (Sn)	7440-31-5		45.0655	mg
			Supplier	Copper (Cu)	7440-50-8		0.2335	mg
Substrate and Solder Mask	49.48	mg	Supplier	Bis(3-ethyl-5-methyl-4- maleimidophenyl)methane	105391-33-1		0.5542	mg

			Supplier	Fiber Glass (SiO2)	65997-17-3	6.4126	mg
			Supplier	Zinc (Zn)	7440-66-6	0.0742	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	1.1529	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer	25722-66-1	0.5542	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.287	mg
			Supplier	Chromium (Cr)	7440-47-3	0.0049	mg
			Supplier	Acetophenone Derivative	Proprietary Data	1.7269	mg
			Supplier	Carbon Black (C)	1333-86-4	0.287	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.287	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	5.9376	mg
			В	Nickel (Ni)	7440-02-0	0.6977	mg
			Supplier	Gold (Au)	7440-57-5	0.0247	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.4587	mg
			Supplier	Formaldehyde Polymer	9003-36-5	0.5542	mg
			Supplier	Copper (Cu)	7440-50-8	18.5352	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.9311	mg
Wire Bond - Au	0.28	mg	Supplier	Gold (Au)	7440-57-5	0.28	mg